NCE3012S

NCE P-Channel Enhancement Mode Power MOSFET

DESCRIPTION

The NCE3012S uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.

GENERAL FEATURES

• $V_{DS} = -30V, I_{D} = -12A$

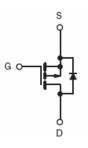
 $R_{DS(ON)}$ < 20m Ω @ V_{GS} =-4.5V

 $R_{DS(ON)}$ < 15m Ω @ V_{GS} =-10V

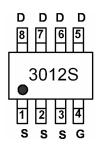
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

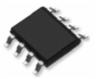
- ●PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin Assignment



SOP-8 top view

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3012S	NCE3012S	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	-12	Α
Drain Current-Pulsed (Note 1)	I _{DM}	-48	Α
Maximum Power Dissipation	P _D	3	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	41.67	°C/W

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						



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NCE3012S

Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)		•	•			
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =-250μA	-1	-1.5	-3	V
Dunin Course On Otata Basistana		V _{GS} =-10V, I _D =-10A	-	-	15	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-7A	-	-	20	mΩ
Forward Transconductance	g fs	V _{DS} =-10V,I _D =-10A	20	-	-	S
Dynamic Characteristics (Note4)		•	•			
Input Capacitance	C_{lss}	\/ 45\/\/ 0\/	-	1750	-	PF
Output Capacitance	C _{oss}	- V _{DS} =-15V,V _{GS} =0V, - F=1.0MHz	-	215	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0WIFI2	-	180	-	PF
Switching Characteristics (Note 4)		•	•			
Turn-on Delay Time	t _{d(on)}		-	9	-	nS
Turn-on Rise Time	t _r	V _{DD} =-15V, ID=-10A,	-	8	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10V, R_{GEN} =1 Ω	-	28	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg		-	24	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =-15V,I _D =-10A,V _{GS} =-10V	-	3.5	-	nC
Gate-Drain Charge	Q _{gd}		-	6	-	nC
Drain-Source Diode Characteristics	<u>.</u>			•		
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-2A	-	-	-1.2	V

Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

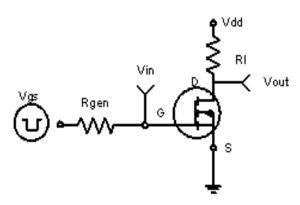
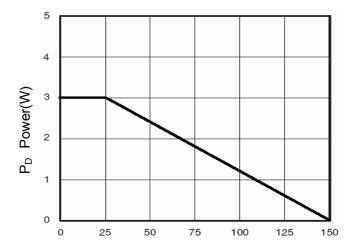


Figure 1:Switching Test Circuit



 T_J -Junction Temperature(${}^{\circ}\mathbb{C}$)

Figure 3 Power Dissipation

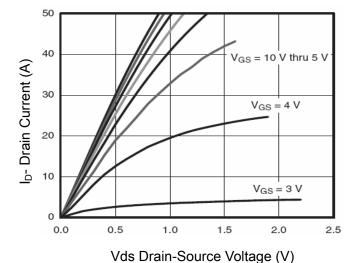


Figure 5 Output CHARACTERISTICS

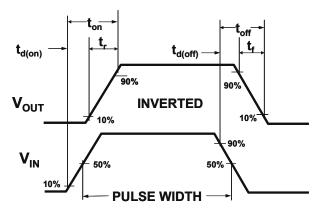


Figure 2:Switching Waveforms

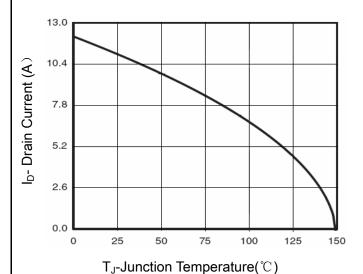


Figure 4 Drain Current

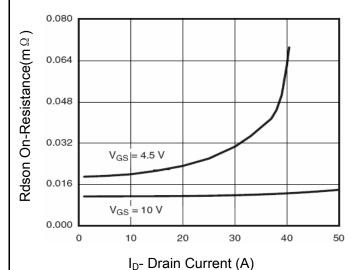
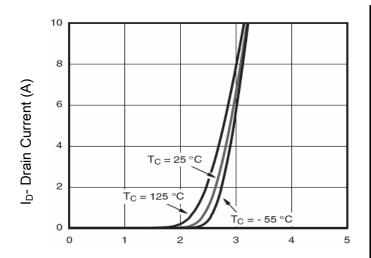
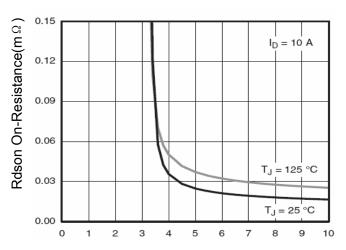


Figure 6 Drain-Source On-Resistance



Vgs Gate-Source Voltage (V)

Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

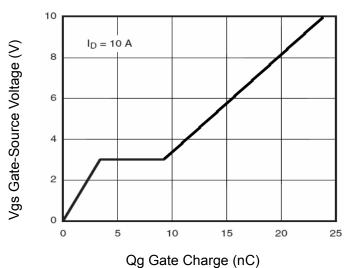
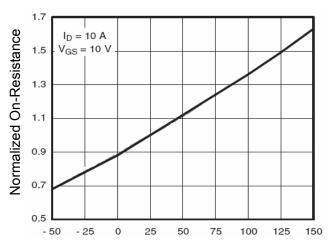
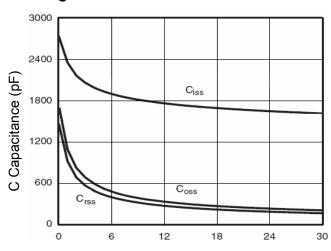


Figure 11 Gate Charge



 T_J -Junction Temperature($^{\circ}$ C)

Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

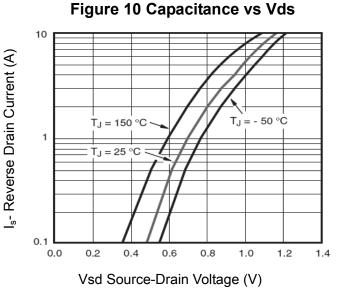
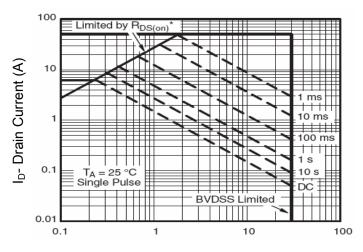


Figure 12 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

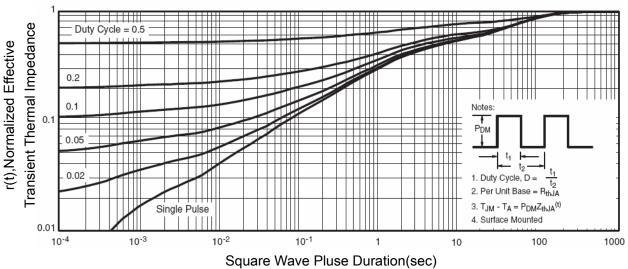
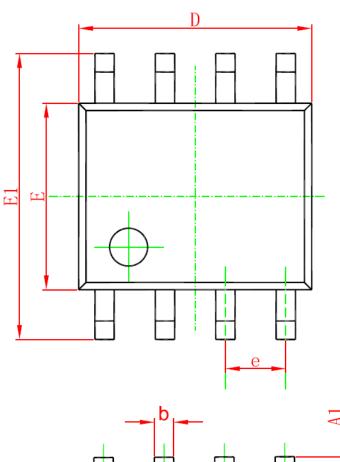
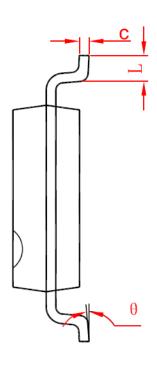
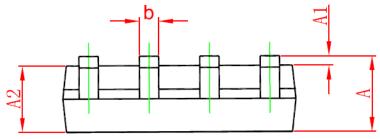


Figure 14 Normalized Maximum Transient Thermal Impedance

SOP-8 PACKAGE IN FORMATION







Ch a l	Dimensions In	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1. 350	1. 750	0. 053	0. 069	
A1	0. 100	0. 250	0.004	0. 010	
A2	1. 350	1. 550	0. 053	0. 061	
b	0. 330	0. 510	0. 013	0. 020	
С	0. 170	0. 250	0.006	0. 010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3. 800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270 (BSC)		0. 050 (BSC)		
L	0. 400	1. 270	0. 016	0. 050	
θ	0°	8°	0°	8°	

Pb Free Product
NCE3012S

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